

File View Edit Tools Window Help

12: (37) 4 and (substrate with contact)
 13: (6) (US-6746880-5 or US-6444027-5 or US-532441)
 14: (36) 12 not 13
 15: (426) (5 not 12) and (substrate with contact)
 16: (291) 15 and electrode
 17: (121) 16 and charge
 18: (99) 17 and current
 19: (99) 18 and surface
 20: (80) 19 and (wir\$4 and (insulat\$4 or dielectric
 21: (67) 20 and etch\$4
 22: (66) 21 and method
 23: (67) 21 and (process or method)
 24: (54) 17 not 23
 25: (9986) substrate and (seal\$4 or (seal\$4 adj (m
 26: (103) 4 not 17
 27: (66) 26 not (12 13 14)
 28: (9910) 25 not 26
 29: (1067) 28 and (seal\$4.ab. and (substrate and (l
 30: (333) 28 and (seal\$4.ab. and (substrate and (b
 31: (104) 30 and electrode

Browser Queue Clear

DBs: USPAT, US-PQPUB, EPO, JPO, IBM, TDB

Default operator: CR

12 not 13

Highlight all items initially

SRM form SRM form SRM form SRM form SRM form

	U	I	PT	P	Document	ID	Issue	Date	Pages	Title	Current	OR	Current
1					US	20040171269	20040902	130		Substrate processing method	438/694		
2					US	20040094328	20040520	61		Cabled signaling system and components thereof	174/251		439/581
3					US	20040077117	20040422	26		Feedthrough design and method for a hermetically sealed microdevice	438/51		438/124;
4					US	20030116087	20030626	16		Chamber hardware design for titanium nitride atomic layer deposition	118/715		438/126;
5					US	20030092261	20030515	132		Substrate processing method	438/638		156/345.
6					US	20020041443	20020411	52		Electrochromic mirrors and devices	359/603		257/E21.
7					US	20020035852	20020328	21		Vacuum IG window unit with edge seal at least partially diffused at temper. and completed via microwave curing, and corresponding method	65/34		5;
8					US	20020020551	20020221	16		CONTROLLED-SHAPED SOLDER RESERVOIRS FOR INCREASING THE VOLUME OF SOLDER BUMPS	174/261		359/601
9					US	6790763	20040914	128		Substrate processing method	438/622		65/41;
10					US	6701749	20040309	22		Vacuum IG window unit with edge seal at least partially diffused at temper. and completed via microwave curing, and corresponding method	65/41		65/43;
11					US	6557248	20030506	28		Method of fabricating an electrostatic chuck	29/825		174/250;
12					US	6399169	20020604	11		Vacuum IG window unit with dual peripheral seal	428/34		174/253;
13					US	6392163	20020521	17		Controlled-shaped solder reservoirs for increasing the volume of	174/261		52/786.1

L Number	Hits	Search Text	DB	Time stamp
1	1105	substrate and (seal\$4 adj ring) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:26
2	1137	substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:27
3	51706	substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:02
4	103	(substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:40
5	1203	(substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:29
6	1	"6579408"	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:35
7	0	6579408.URPN.	USPAT	2004/10/20 11:35
8	0	6579408.URPN.	USPAT	2004/10/20 11:36
9	4	("5275690" "5324410" "5578167" "6171437").PN.	USPAT	2004/10/20 11:36
10	4	("5275690" "5437757" "5542559" "5695566").PN.	USPAT	2004/10/20 11:37
11	3	6171437.URPN.	USPAT	2004/10/20 11:37
12	37	((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:43
13	6	(US-6746880-\$ or US-6444027-\$ or US-5324410-\$ or US-6579408-\$ or US-6171437-\$).did. or (US-20040104402-\$).did.	USPAT; US-PGPUB	2004/10/20 11:40
14	36	((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact)) not ((US-6746880-\$ or US-6444027-\$ or US-5324410-\$ or US-6579408-\$ or US-6171437-\$).did. or (US-20040104402-\$).did.)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:41
15	426	((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:44

16	291	(((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:44
17	121	(((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:45
18	99	((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:45
19	99	((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:46
20	80	(((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge) and current) and surface) and (wir\$4 and (insulat\$4 or dielectric) electrolyt\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:01

21	67	((((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring)))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact) and electrode) and charge) and current) and surface) and (wir\$4 and (insulat\$4 or dielectric) electrolyt\$3)) and etch\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:48
22	66	((((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring)))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact) and electrode) and charge) and current) and surface) and (wir\$4 and (insulat\$4 or dielectric) electrolyt\$3)) and etch\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:48
23	67	((((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring)))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact) and electrode) and charge) and current) and surface) and (wir\$4 and (insulat\$4 or dielectric) electrolyt\$3)) and etch\$4) and (process or method)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:51

24	54	((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring)))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact) and electrode) and charge) not (((((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact) and electrode) and charge) and current) and surface) and (wir\$4 and (insulat\$4 or dielectric) electrolyt\$3)) and etch\$4) and (process or method))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:51
25	9986	substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))).clm. and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:02
26	103	((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not ((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact) and electrode) and charge)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:03

27	66	(((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not ((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact)) ((US-6746880-\$ or US-6444027-\$ or US-5324410-\$ or US-6579408-\$ or US-6171437-\$).did. or (US-20040104402-\$).did.) (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact)) not ((US-6746880-\$ or US-6444027-\$ or US-5324410-\$ or US-6579408-\$ or US-6171437-\$).did. or (US-20040104402-\$).did.)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:07
28	9910	(substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))).clm. and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not ((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:07

29	1067	((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))).clm. and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not ((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal\$4.ab. and (substrate and (body or base or board or plate).ab.))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:08
30	333	((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))).clm. and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not ((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4)) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal\$4.ab. and (substrate and (body or base or board or plate).ab.))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:08

31	196	((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))).clm. and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4) not ((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal\$4.ab. and (substrate and (body or base or board or plate)).ab.)) and electrode	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:09
32	85	((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))).clm. and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4) not ((((((substrate and (seal\$4 or (seal\$4 adj (mean\$3 or ring))) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4) not (((substrate and (seal\$4 adj (mean\$3 or ring)) and (gas or liquid) and (open\$4 or hole or trench) and (base or board or plate or body) and conduct\$4) and ((outer or second or inner) adj seal\$4) and (substrate with contact))) and (substrate with contact)) and electrode) and charge))) and (seal\$4.ab. and (substrate and (body or base or board or plate)).ab.)) and electrode.ab.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 12:09
-	34	birner-albert.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/20 11:22
-	71	franosch-martin.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:07
-	57	goldbach-matthias.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:07
-	150	lehmann-volker.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:08
-	16	lutzen-jorn.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:08

-	262	birner-albert.in. franosch-martin.in. goldbach-matthias.in. lehmann-volker.in. lutzen-jorn.in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:08
-	3	(birner-albert.in. franosch-martin.in. goldbach-matthias.in. lehmann-volker.in. lutzen-jorn.in.) and (seal\$4 adj ring) and substrate and (board or base or plate) and (hole or open\$4) and conduct\$4	USPÄT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:17
-	9	("4428815" "4876224" "5209833" "5437777" "5463526" "5511428" "5911461" "6217724" "6444027").PN.	USPAT	2004/10/19 19:11
-	15	("4322592" "4496609" "5192371" "5200157" "5242501" "5516367" "5679405" "5769942" "5856240" "5904769" "5960555" "6103014" "6127286" "6129047" "6184154").PN.	USPAT	2004/10/19 19:14
-	4	("5071510" "5209833" "5324410" "6120657").PN.	PNSPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/10/19 19:17
-	3	("4043894" "4696729" "5126031").PN.	USPÄT	2004/10/19 19:18
-	12	5324410.URPN.	USPAT	2004/10/19 19:18